PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHIH-HSUAN TAI	08/10/2018
HAO-YI TSAI	08/10/2018
YU-CHIH HUANG	08/10/2018
CHIA-HUNG LIU	08/10/2018
TING-TING KUO	08/10/2018
BAN-LI WU	08/17/2018
YING-CHENG TSENG	08/10/2018
CHI-HUI LAI	08/10/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
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State/Country:	TAIWAN
Postal Code:	300-78

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16103921

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	79883-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/

DATE SIGNED:	09/28/2018

Total Attachments: 4

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

PACKAGE STRUCTURE, PACKAGE-ON-PACKAGE STRUCTURE AND METHOD OF FABRICATING THE SAME

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number

______________Filed on _________________

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Chih-Hsuan Tai Date: 2018. 8. 10

Legal Name of Sole or First Inventor: **Chih-Hsuan Tai**

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hao-Yi Tsai Date: 2018. 8. 10

Legal Name of Additional Joint Inventor, if any: **Hao-Yi Tsai**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Yu-chih Huang Date: 2018, 08, 10

Legal Name of Additional Joint Inventor, if any: **Yu-Chih Huang**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chia-Hung Liu Date: 2018.8.10.

Legal Name of Additional Joint Inventor, if any: **Chia-Hung Liu**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ting-Ting Kuo Date: 2018. 8. 10

Legal Name of Additional Joint Inventor, if any: **Ting-Ting Kuo**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

DECLARATION AND ASSIGNMENT

FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Ban-Li Wu Date: 2018/8/17

Legal Name of Additional Joint Inventor, if any: **Ban-Li Wu**

Residence: Hsinchu, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ying-Cheng Tseng Date: 2018/8/10

Legal Name of Additional Joint Inventor, if any: **Ying-Cheng Tseng**

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Signature: Chi-Hui Lai Date: 2018/8/10

Legal Name of Additional Joint Inventor, if any: **Chi-Hui Lai**

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